



19th IEEE Electrical Design of Advanced Packaging and Systems (EDAPS) Symposium

14th December – 16th December, 2026

Chandigarh, INDIA

Sponsorship and Exhibitor Opportunities

EDAPS is the premier international conference in the Asia-Pacific region on advanced and emerging issues in the electrical modeling, analysis, and design of electronic interconnections, packages, and systems. Over three days, the conference will feature the latest advancements in CAD, design, and measurement techniques for:

- ensuring signal, power, and thermal integrity in high-speed systems;
- optimizing performance in high-speed, RF, wireless and quantum systems.
- enabling heterogeneous integration and packaging for chiplets

We are excited to add a student software competition that will give a platform to young prospective tech-preneurs to showcase their software in the fields of packaging (auto-routing, SI/PI/EMC analysis, reliability-thermal analysis, co-optimization and design)

EDAPS 2026 will be held on the campus of IIT Ropar, a dynamic campus amidst the hills with a thriving student and faculty body, with close proximity to Chandigarh, one of the three that forms the Tri-City soon becoming the IT and Technology hub of Northern India.

With an estimate of more than 100 participants from industry and academia all over the globe, we believe EDAPS 2026 will be an excellent opportunity for your organization to promote its products/services, strengthen its brand recognition in the leading international venue in the area, connect with experts and potential customers, and recruit top talents. Please find in the next page the sponsorship and exhibitor opportunities that EDAPS 2026 will offer.

We look forward to seeing you at IIT-Ropar!

Prof. Rohit Sharma, IIT
Ropar
General Co-chair
rohit@iitrpr.ac.in

Dr. Nikita Ambasana,
Simyog
General Co-chair
nikita@simyog.com

Dr. Anushruti Jaiswal,
Synopsys
Sponsorship Chair,
anushruti.jaiswal@ansys.com

EDAPS is sponsored by:



Package	Platinum	Gold	Silver	Bronze/Exhibitor	Student Software Prize
Fee (INR)	> Rs. 5,00,000	Rs. 5,00,000	Rs. 3,00,000	Rs 1,00,000	Rs 1,00,000
Maximum number of sponsors	2				2
Demo/presentation* in main conference room	20 mins	10 mins			
Training program* to attendees in separate room	1 h	½ h			
Special recognition	Lunch on Day 2 and 3 of conference	Lunch on day of demo (day2 or 3)			
Logo on attendee's lanyard*	✓	✓			
Space in conference proceedings*	2 pages	1 page	½ page		
Promotional brochure or merchandise included in workshop kit*	✓	✓	✓		
Logo* and link included in the conference website and proceedings	✓	✓	✓	✓	
Logo* on the Student Software Prize and Prize will be named for the sponsor					✓
Exhibition space (table and 2 chairs, electrical socket, wi-fi)	✓	✓	✓	✓	
Recognition during opening and closing ceremonies	✓	✓	✓	✓	✓
Full registrations included	4	2	1	1	1
Discounted registrations included (50% discount)	4	2	1	-	1

*: material to be provided by the sponsors or exhibitors

To register as a sponsor or exhibitor, please email anushruti.jaiswal@ansys.com or nikita@simyog.com

EDAPS is sponsored by:

